

SMG2325-VB Datasheet N-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)		
200	1.4 at V _{GS} = 10 V	0.6		

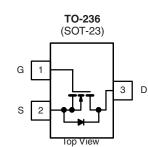
FEATURES

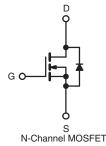
- Halogen-free According to IEC 61249-2-21
 Definition
- 100 $\%~\text{R}_{g}$ and UIS Tested
- Trench Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



HALOGEN

FREE Available





ABSOLUTE MAXIMUM RATINGS	(T _A = 25 °C, unle	ess otherwise i	noted)			
Parameter		Symbol	5 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	200		V	
Gate-Source Voltage		V _{GS}	± 20			
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 25 °C	1	0.6	0.45		
	T _A = 70 °C	- I _D	0.5	0.35		
Pulsed Drain Current ^b		I _{DM}	2.5		A	
Avalanche Current ^b	L = 0.1 mH	I _{AS}	2.5			
Single Avalanche Energy	L = 0.1 IIIH	E _{AS}	50		mJ	
Continuous Source Current (Diode Conduction) ^a		۱ _S	0.6		А	
Power Dissipation ^a	T _A = 25 °C	1.55 1.03		1.03	W	
	T _A = 70 °C	PD	1.20	0.87	vv	
Operating Junction and Storage Temperature Range		T _{.I} , T _{sta}	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 5 s	R _{thJA}	80	100		
Maximum Sunction-to-Ambient	Steady State		130	170	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	45	55		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. Pulse width limited by maximum junction temperature.



SPECIFICATIONS (T _A = 25 °C, unless otherwise noted)							
			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 1 mA$	200			v	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.5		4.5	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zara Cata Valtaga Drain Current	1	V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 ^{\circ}\text{C}$			75	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 15$ V, $V_{GS} = 10$ V	2.5			А	
Drain-Source On-Resistance ^a	R _{DS(on)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 0.5 \text{ A}$		1.4		Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 0.5 \text{ A}$		4		S	
Diode Forward Voltage	V _{SD}	I _S = 1 A, V _{GS} = 0 V		0.8	1.2	V	
Dynamic ^b							
Total Gate Charge	Qg			3	5		
Gate-Source Charge	Q _{gs}	V_{DS} = 100 V, V_{GS} = 10 V, I_{D} = 0.5 A		0.37		nC	
Gate-Drain Charge	Q _{gd}			1.45			
Gate Resistance	Rg		0.5	1.3	2.4	Ω	
Switching							
Turn-On Delay Time	t _{d(on)}			7	11		
Rise Time	t _r	V_{DD} = 100 V, R_{L} = 33 Ω		10	15]	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 0.2$ A, V_{GEN} = 10 V, R_g = 6 Ω		9	15	ns	
Fall Time	t _f			11	15]	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 0.5 A, dl/dt = 100 A/μs50100					

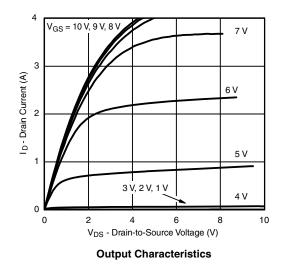
Notes:

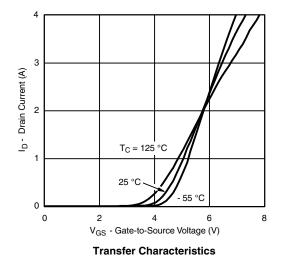
a. Pulse test: PW \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

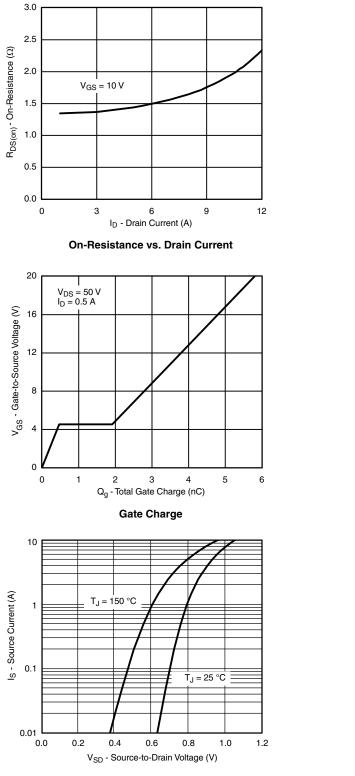
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



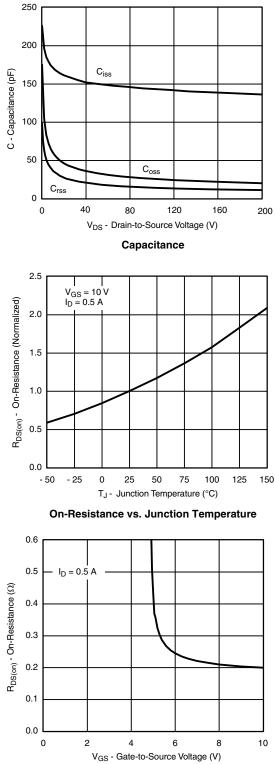






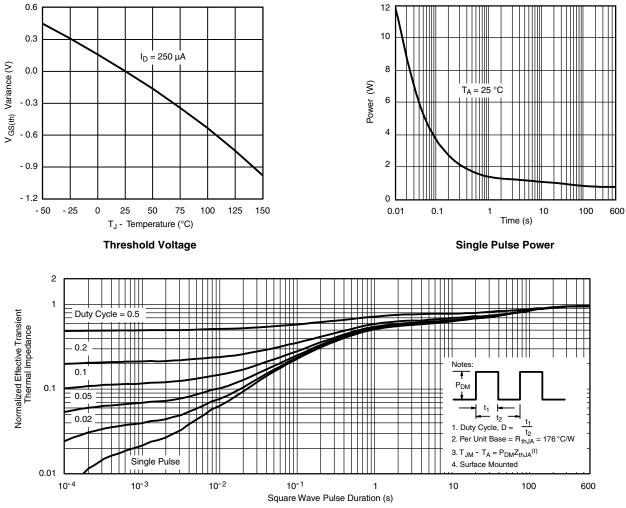


Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



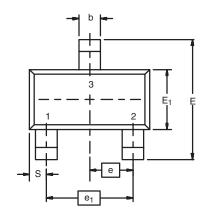


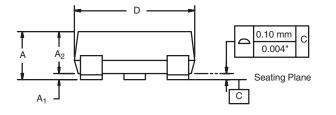
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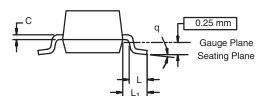
Normalized Thermal Transient Impedance, Junction-to-Ambient



SOT-23 (TO-236): 3-LEAD



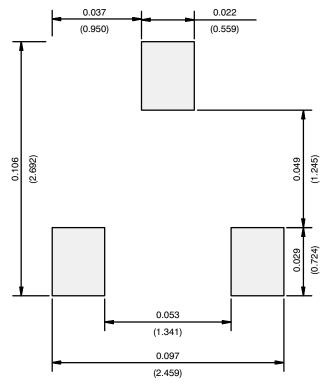




Dim	MILLIN	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
C	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8 °	
ECN: S-03946-Rev. K, 09- DWG: 5479	Jul-01				



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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